



# SOT815-1

plastic, leadless dual in-line compatible thermal enhanced very thin quad flat package; 24 terminals; 0.5 mm pitch; 5.5 mm x 3.5 mm x 1 mm body

17 August 2021

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	DHVQFN24
<b>Package type industry code</b>	DHVQFN24
<b>Package style descriptive code</b>	DHVQFN (DIL-compatible thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Number of package outline detail graphic references</b>	0
<b>Issue date</b>	29-4-2003
<b>Manufacturer package code</b>	SOT815
<b>Footprint dimensions (mm)</b>	6.75 x 4.75
<b>Footprint area (mm<sup>2</sup>)</b>	32.06

Table 1. Package summary

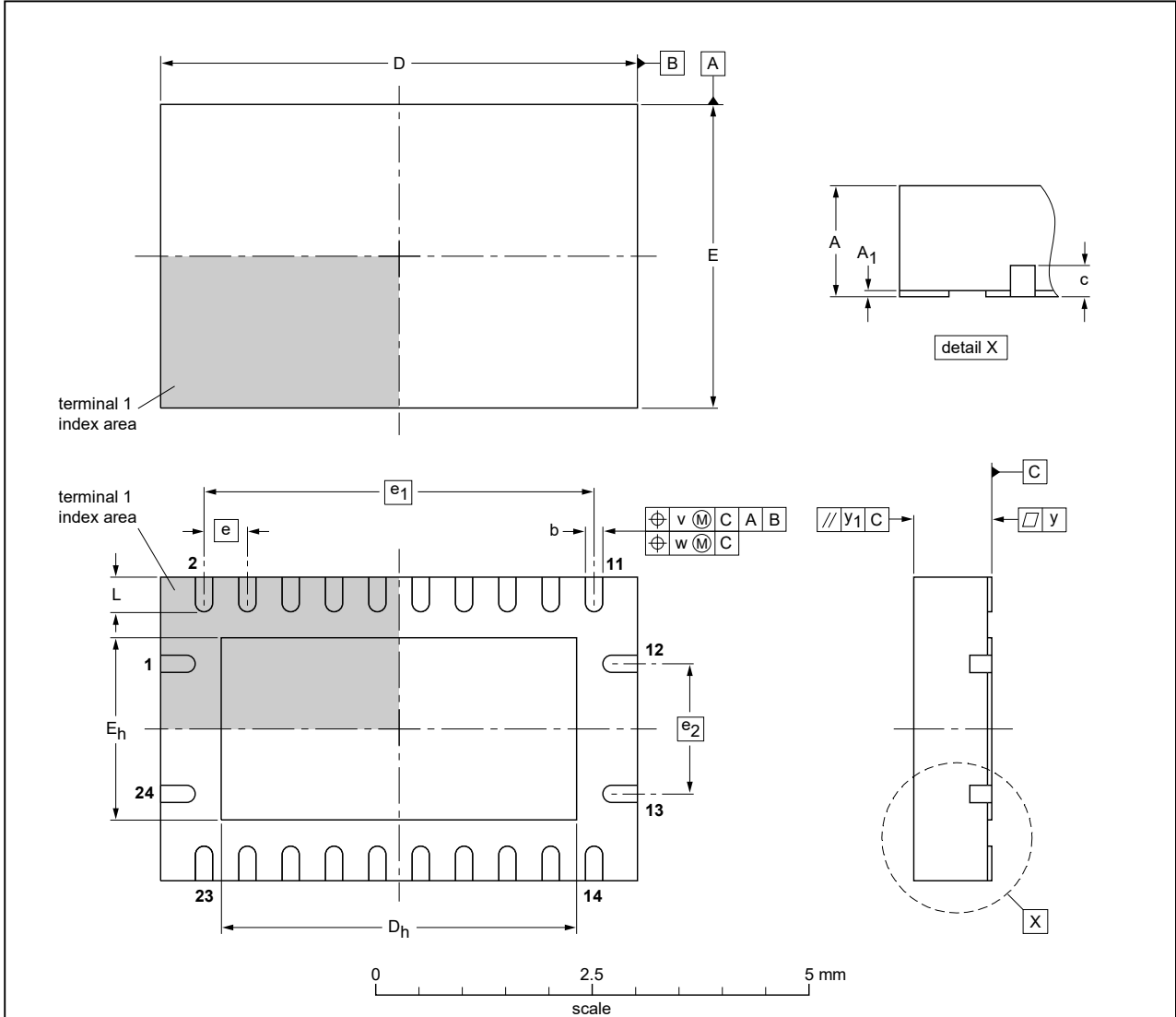
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.4	-	5.5	5.6	mm
E	package width	3.4	-	3.5	3.6	mm
A	seated height	-	-	0.85	1	mm
A <sub>2</sub>	package height	-	-	0.85	-	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	24	-	

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## 2. Package outline

DHVQFN24: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3.5 x 5.5 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sup>(1)</sup> max.	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.30 0.18	0.2	5.6 5.4	4.25 3.95	3.6 3.4	2.25 1.95	0.5	4.5	1.5	0.5 0.3	0.1	0.05	0.05	0.1

**Note**

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT815-1	---	---	---			03-04-29

Fig. 1. Package outline DHVQFN24 (SOT815-1)

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### 3. Soldering

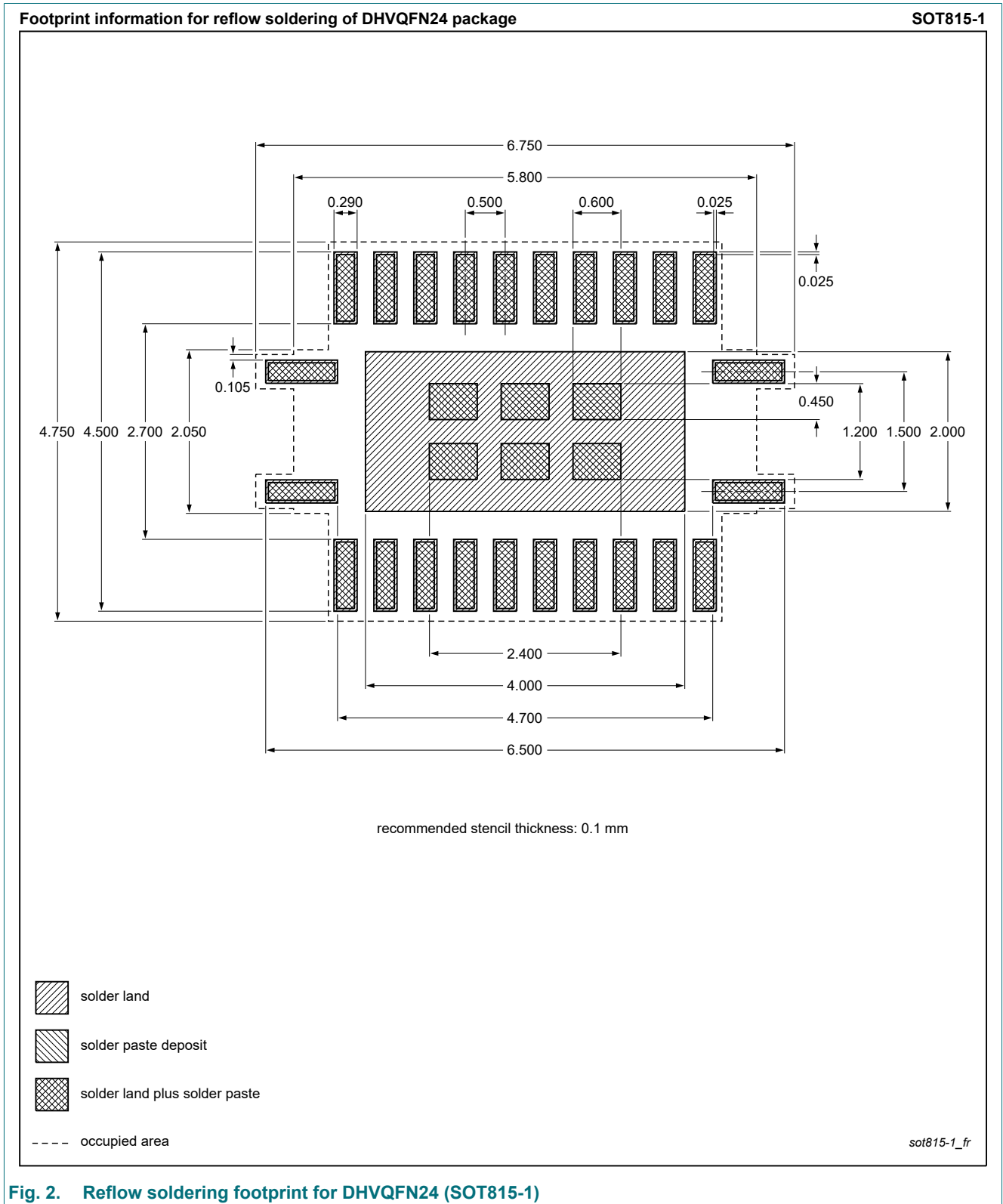


Fig. 2. Reflow soldering footprint for DHVQFN24 (SOT815-1)

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